

Product Information Sheet

CP-0317

EVA HM Holz-Her I

Application Temperature(s): 200-220°C (Thermostat)
 Color: Ivory
 Freeze Thaw Stable: NA
 Min Use Temperature: NA
 Shelf Life: Approx. 2 years
 Solids (~): NA
 Specific Gravity (~): 1.3 g/cm³
 Viscosity :
 at 180°C 110,000±20,000 mPa s
 at 200°C 65,000±10,000 mPa s



Characteristics:

Basis: Ethylene-Vinylacetate-Copolymer
 Edge banding cartridge designed in conjunction with Holzher
 Features a slide coating to reduce maintenance

Applications:

Field of Application: Bonding of HPL edges, epoxy resin edges, ABS edges, Solid wood edges, Polyester edges, PVC- edges, Veneer edges

Directions:

Melting Index DIN 53 735 (MFI 150/2.16) 60±15 g/10 min.
 Pre heat time 2-5 minutes
 Speed 8-20 m/min. depending on machine
 Heat resistance up to +80°C depending on edge
 Cold resistance up to -20°C depending on edge
 Product formant cartridge Ø: 63±0.5 mm
 length: 80±2.0 mm

Application: Both substrates have to be cut to an exact right angle and must be free from dust. Bring the substrate and the edging material up to room temperature. The ideal moisture content of the wood is 8 - 10%, room temperature of min. 18°C, avoid drafts. Preheat time 2-5 minutes, application temperature 200-220°C (Thermostat). Correct temperature settings are especially important when bonding HPL and solid wood edges. When bonding long and/or ridges pieces the application temperature should be in the higher temperature areas. Lower temperatures reduce the "wetting out" of the edges. Coat weight and press pressure should be adjusted so that the applied beads are pressed flat and the adhesives quills out on the edges slightly. To determine the correct coat weight the use of a transparent edge is advised.

Note: For solid wood edging the use of linear grain wood is preferable as this is less prone to bend. To achieve optimum bond strength the wood grain of the edges should be vertical on the bond surface. Prepare the base substrate exactly. The chipboard should have a surface which does not have cutting marks. Adjust the press tolerance to be a little bit lower than the width of the edge.

Clean Up and Storage:

When cleaning the application equipment observe the manufacturers instructions.
 Store cool, dry and in original sealed packaging.

Key warnings:

Disposal Hardened adhesive domestic waste disposal
 When hot melt adhesives are melted and applied, vapours are set free and an unpleasant odour can occur, even if the recommended working temperature has been observed. If the recommended working

temperature is exceeded over a long period of time, harmful decomposition products can develop. Precautions should be taken i.e. using suitable ventilation, to eliminate vapours.

Softening Point: (Ring and Ball) DIN 1995 $110^{\circ}\text{C}\pm 5^{\circ}\text{C}$